

## REMARKS

Reconsideration of the present application, as amended, is respectfully requested. Claim 13 has been amended. Therefore, claims 13-54 are presented for Examiner.

Applicants wish to thank the Examiner for finding claims 53 and 54 allowable.

Examiner rejected claims 13, 14, 42-43, and 50 under 35 U.S.C. §102(b) as being anticipated by U.S. Patent No. 4,416,056 to Takahashi. Takahashi discusses a process for preparation of film coils, including multiple layers of spiral patterns wound in reverse directions. The Examiner suggests that Takahashi has a post with protective and conductive layers on it, but suggesting that layer 16 is a post. However, Takahashi is very clear that "a second conductor pattern 16 is formed in slit portion 15 between adjacent segments of the first layer conductor pattern 11." (Takahashi, column 3, lines 31-35). Therefore, layer 16 of Takahashi is not a post, and cannot in any way be considered equivalent to a post. In fact, Takahashi does not teach or suggest a post, over which a conductive layer is deposited. Furthermore, Takahashi does not teach or suggest that this process produces a packaged inductor, in which the posts may be used to couple the inductor to another device. Rather, Takahashi discusses a resulting magnetic head, but does not discuss packaging.

Claim 13 recites:

A packaged inductor comprising:  
a substrate;  
a first insulating layer over the substrate;  
posts over the insulating layer;  
a conductive layer deposited on top of the posts and in a pattern on  
the substrate, the conductive layer on the tops of the posts for coupling  
the packaged inductor to another device.

(Claim 13, as amended). As noted above, Takahashi does not teach or suggest a post, or a packaged inductor. Therefore, claim 13, and claims 14-19 which depend on it are not anticipated by Takahashi.

Claim 42 recites:

A packaged inductor comprising:  
a substrate including a plurality of posts having a top;  
conductive layer a pattern on the substrate to form an inductor, the  
conductive layer extending to the top of the posts;  
a first insulating layer over the conductive layer; and  
the top of the posts used for coupling the packaged inductor to  
another device.

As noted above, Takahashi does not teach or suggest a plurality of posts having a top, nor the tops of posts used for coupling the packaged inductor to another device. Therefore, claim 42, and claims 43-52 which depend on it, are not obvious over or anticipated by Takahashi.

Examiner rejected claims 13, 42, and 50 under 35 U.S.C. §102(b) as being anticipated by U.S. Patent No. 4,152,679 to Chen. Chen discusses a microminiature electrical delay line that utilizes an m-derived filter formed by depositing a film of permalloy or other high permeability metal on a quartz or other dielectric substrate. The Examiner suggests that film 22 is equivalent to the posts. However, Chen specifically describes film 22, as “plurality of superimposed coaxial turns 20 of electrically conductive metal film with adjacent turns [are] isolated electrically from each other by an interposed film 22 of dielectric material. (Chen, column 2, lines 38-42) Thus, interposed film 22 is the insulating layer, rather than a post. There is no suggestion in Chen of a post, the top of which may be used for coupling the packaged inductor to another device. In fact, Chen does not teach or suggest “packaging” Furthermore,

rather than using the tops of posts for coupling the packaged inductor, Chen uses a pair of electrically conductive terminals 16 and 18 are deposited upon the dielectric film 14, adjacent one side of the substrate, for use in connecting the delay line to associated hybrid circuits. (Chen, column 2, lines 24-27).

Claim 13 recites:

A packaged inductor comprising:  
a substrate;  
a first insulating layer over the substrate;  
posts over the insulating layer;  
a conductive layer deposited on top of the posts and in a pattern on the substrate, the conductive layer on the tops of the posts for coupling the packaged inductor to another device.

(Claim 13, as amended). As noted above, Chen does not teach or suggest a post, or a packaged inductor. Therefore, claim 13, and claims 14-19 which depend on it are not anticipated by Chen.

Claim 42 recites:

A packaged inductor comprising:  
a substrate including a plurality of posts having a top;  
conductive layer a pattern on the substrate to form an inductor, the conductive layer extending to the top of the posts;  
a first insulating layer over the conductive layer; and  
the top of the posts used for coupling the packaged inductor to another device.

As noted above, Chen does not teach or suggest a plurality of posts having a top, nor the tops of posts used for coupling the packaged inductor to another device. Therefore, claim 42, and claims 43-52 which depend on it, are not obvious over or anticipated by Chen.

Examiner rejected claims 15, 16, and 44-46 under 35 U.S.C. §103(a) as being unpatentable over Chen in view of U.S. Patent No. 5,208,656 to Matsuyama et al.

Examiner rejected claims 17, 47, and 49 under 35 U.S.C. §103(a) as being

unpatentable over Chen in view of U.S. Patent No. 5,393,697 to Chang et al. Examiner rejected claims 18 and 44-46 under 35 U.S.C. §103(a) as being unpatentable over Takahashi in view of Matsuyama. Examiner rejected claims 19 and 47 under 35 U.S.C. §103(a) as being unpatentable over Chen in view of Matsuyama as applied to claim 16 above, and further in view of Chang.

Applicants respectfully submit that none of these references, alone or in combination overcome the limitations of Chen, discussed above. In particular, none of these references teach or suggest the use of posts, nor the use of the tops of posts used to couple a packaged inductor to another device. Therefore, at least the arguments made above with respect to claims 13 and 42 above apply to the suggested combination of references. Thus, Applicants respectfully submit that these claims are not obvious over a combination of Chan, Matsuyama, Chang, and Takahashi.

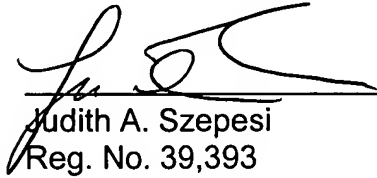
Applicant respectfully submits that in view of the amendments and discussion set forth herein, the applicable rejections have been overcome. Accordingly, the present and amended claims should be found to be in condition for allowance.

If a telephone interview would expedite the prosecution of this application, the Examiner is invited to contact Judith Szepesi at (408) 720-8300.

If there are any additional charges/credits, please charge/credit our deposit  
account no. 02-2666.

Respectfully submitted,  
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